Photocouplers Photorelay

TLP241BP, TLP241BPF

1. Applications

- Heating, ventilation and air conditioning (HVAC)
- Factory Automation (FA)
- Battery Management System (BMS) (Non-Automotive)
- Mechanical relay replacements

2. General

The TLP241BP and TLP241BPF photorelay consist of a photo MOSFET optically coupled to an infrared light emitting diode. They are housed in a 4-pin DIP package. They provide an isolation voltage of 5000 Vrms, making them suitable for applications that require reinforced insulation.TLP241BP has over temperature protection (OTP) and over voltage protection (OVP). So it contributes to reliability of equipment.

3. Features

(1) Protection: Over Temperature Protection 145°C (typ.), Over Voltage Protection
(2) Normally opened (1-Form-A)
(3) OFF-state output terminal voltage: 80 V (min)
(4) Trigger LED current: 3 mA (max)
(5) ON-state current: 1.4 A (max)
(6) ON-state resistance: 280 mΩ (max)
(7) Isolation voltage: 5000 Vrms (min)
(8) Halogen-free
For details, see "Devices in Halogen-Free Resin Packages" at the end of this datasheet.
(9) Safety standards
UL-recognized: UL 1577, File No.E67349
cUL-recognized: CSA Component Acceptance Service No.5A File No.E67349
VDE-approved: EN 60747-5-5 **(Note 1)**

Note 1: When an EN 60747-5-5 approved type is needed, please designate the **Option (D4)**.

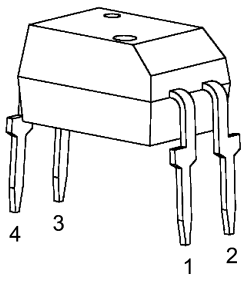
4. Mechanical Parameters

Characteristics	7.62-mm Pitch TLP241BP	10.16-mm Pitch TLP241BPF	Unit
Creepage distances	7.0 (min)	8.0 (min)	mm
Clearance distances	7.0 (min)	8.0 (min)	
Internal isolation thickness	0.4 (min)	0.4 (min)	

Start of commercial production
2023-10

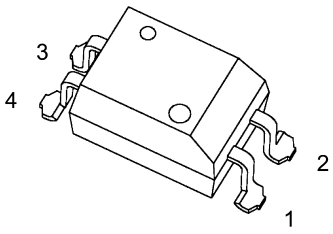
5. Packaging (Note)

TLP241BP



11-5B2S

TLP241BP(LF1,TP1)



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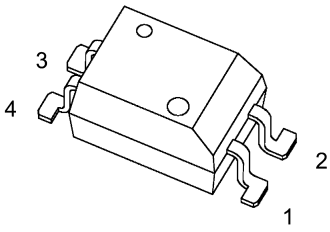

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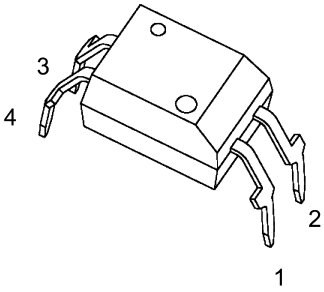
TLP241BPF



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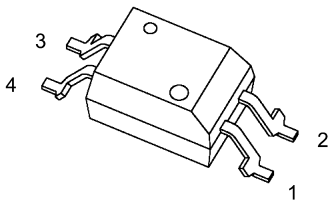
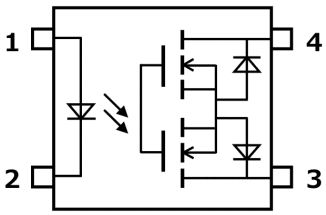


11-5B204S

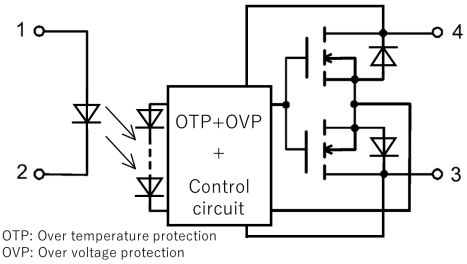
Note: Through-hole type: TLP241BP, TLP241BPF
Lead forming option: (LF1), (LF4), (LF5)
Taping option: (TP1), (TP4), (TP5)

6. Pin Assignment



1: Anode
2: Cathode
3: Drain
4: Drain

7. Internal Circuit



OTP: Over temperature protection
OVP: Over voltage protection

8. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics		Symbol	Note	Rating	Unit
LED	Input forward current		I_F		20	mA
	Input forward current derating	($T_a \geq$ 97 °C)	$\Delta I_F/\Delta T_a$		-0.71	mA/°C
	Input reverse voltage		V_R		6	V
	Input power dissipation		P_D		40	mW
	Input power dissipation derating	($T_a \geq$ 97 °C)	$\Delta P_D/\Delta T_a$		-1.43	mW/°C
	Junction temperature		T_j		125	°C
Detector	OFF-state output terminal voltage		V_{OFF}		80	V
	ON-state current		I_{ON}		1.4	A
	ON-state current derating	($T_a \geq$ 25 °C)	$\Delta I_{ON}/\Delta T_a$		-14	mA/°C
	ON-state current (pulsed)	(t = 100 ms, Duty = 1/10)	I_{ONP}		4.2	A
	Output power dissipation		P_O		550	mW
	Output power dissipation derating	($T_a \geq$ 25 °C)	$\Delta P_O/\Delta T_a$		-5.5	mW/°C
	Junction temperature		T_j		125	°C
Common	Storage temperature		T_{stg}		-55 to 125	°C
	Operating temperature		T_{opr}		-40 to 110	°C
	Lead soldering temperature	(10 s)	T_{sol}		260	°C
	Isolation voltage	AC, 60 s, R.H. ≤ 60 %	BV_S	(Note 1)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

9. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Input forward current	I_F		7	—	14	mA

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this data sheet should also be considered.

10. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		I_F = 10 mA	1.50	1.65	1.80	V
	Input reverse current	I_R		V_R = 6 V	—	—	10	μA
	Input capacitance	C_t		V = 0 V, f = 1 MHz	—	50	—	pF
Detector	OFF-state current	I_{OFF}		V_{OFF} = 40 V	—	—	1	μA
	OFF-state current	I_{OFF}		V_{OFF} = 60 V	—	—	10	μA
	Output capacitance	C_{OFF}		V = 0 V, f = 1 MHz	—	130	—	pF
	Over voltage clamp	V_{OVC}		I_F = 0 mA, I_{OFF} = 10 mA, t = 10 μs	80	—	100	V

11. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Trigger LED current	I_{FT}		I_{ON} = 1.0 A	—	1	3	mA
Return LED current	I_{FC}		I_{OFF} = 10 μA	0.01	—	—	
ON-state resistance	R_{ON}		I_{ON} = 1.4 A, I_F = 10 mA, t < 1 s	—	0.16	0.28	Ω
Thermal shutdown temperature	T_{SD}		I_{OFF} = 10 μA, I_F = 10 mA	—	145	—	°C

12. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	V_S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	V_S = 500 V, R.H. ≤ 60 %	10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	5000	—	—	Vrms

Note 1: This device is considered as a two-terminal device: Pins 1 and 2 are shorted together, and pins 3 and 4 are shorted together.

13. Switching Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Turn-on time	t_{ON}		See Fig. 13.1. R_L = 200 Ω, V_{DD} = 20 V, I_F = 10 mA	—	0.4	1.4	ms
Turn-off time	t_{OFF}			—	0.03	0.5	

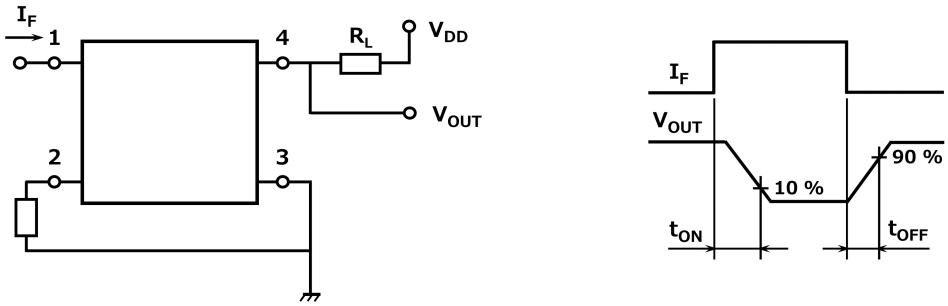


Fig. 13.1 Switching Time Test Circuit and Waveform

14. Characteristics Curves (Note)

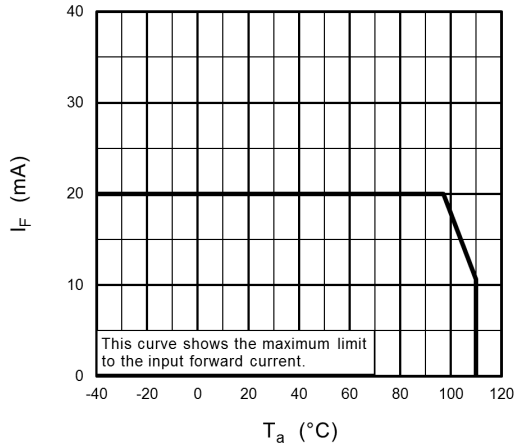


Fig. 14.1 I_F - T_a

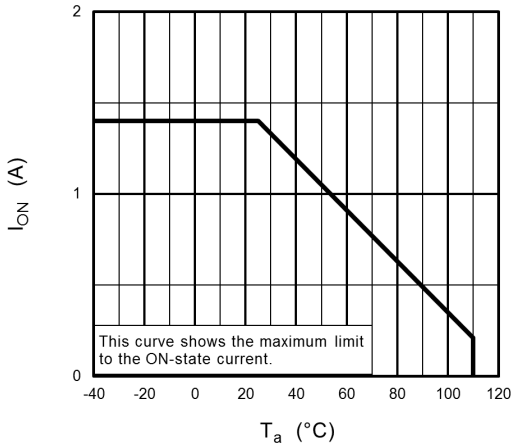


Fig. 14.2 I_{ON} - T_a

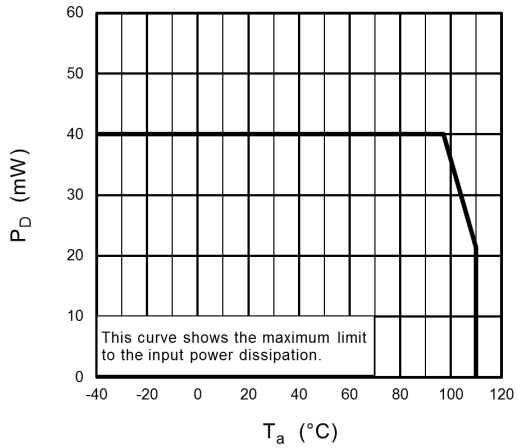


Fig. 14.3 P_D - T_a

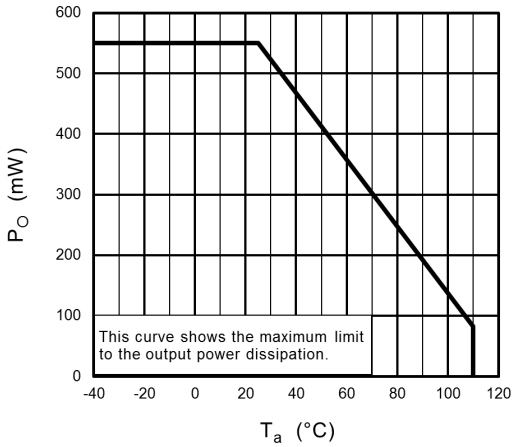


Fig. 14.4 P_O - T_a

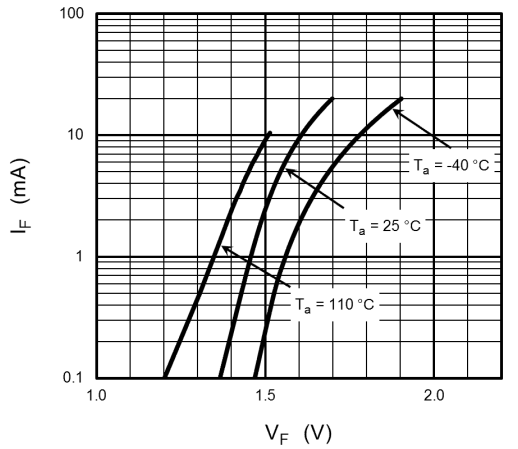


Fig. 14.5 I_F - V_F

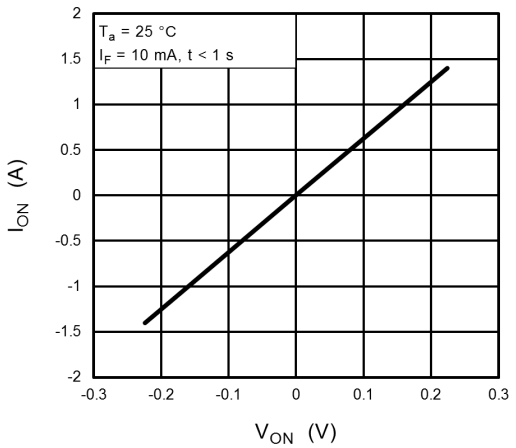


Fig. 14.6 I_{ON} - V_{ON}

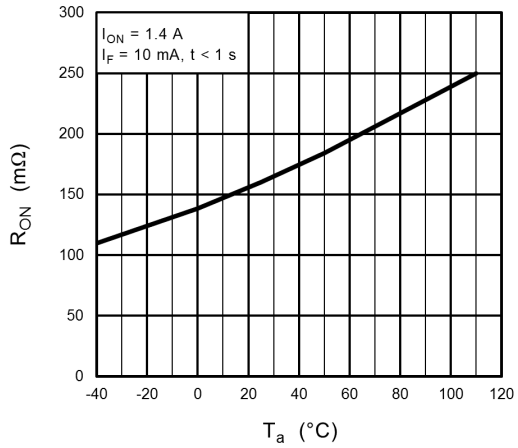


Fig. 14.7 R_{ON} - T_a

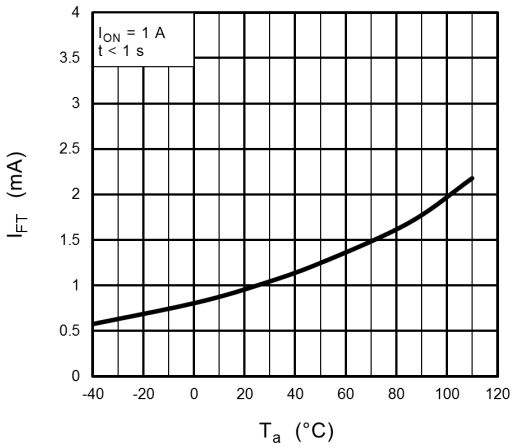


Fig. 14.8 I_{FT} - T_a

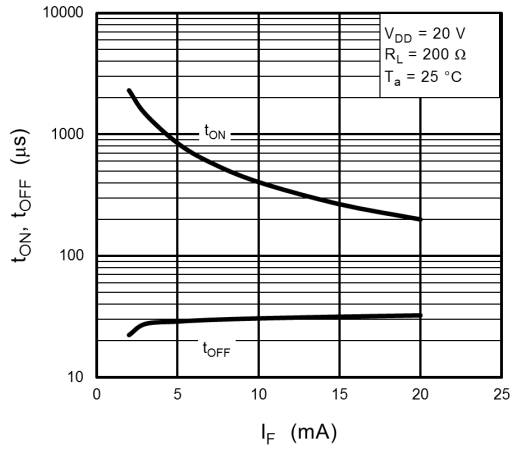


Fig. 14.9 t_{ON}, t_{OFF} - I_F

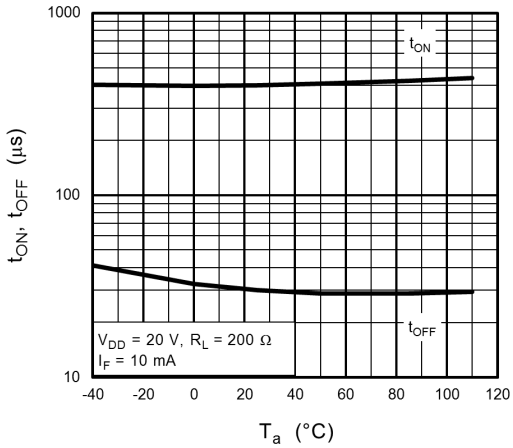


Fig. 14.10 t_{ON}, t_{OFF} - T_a

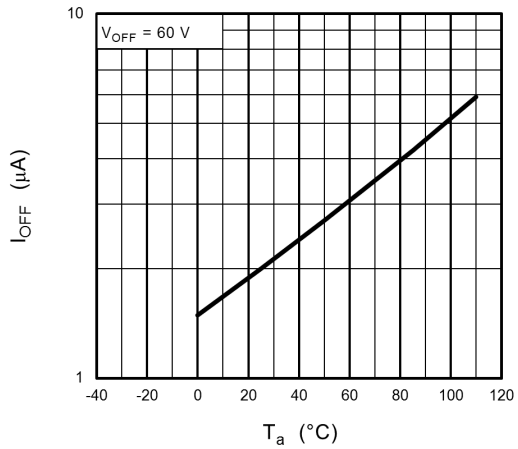


Fig. 14.11 I_{OFF} - T_a

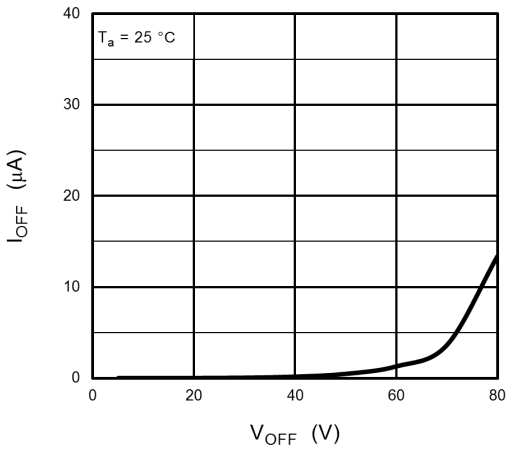


Fig. 14.12 I_{OFF} - V_{OFF}

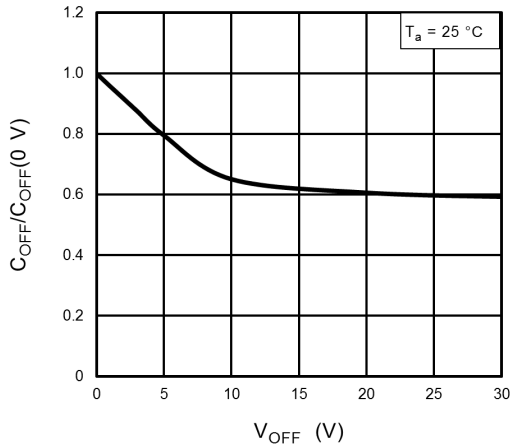


Fig. 14.13 C_{OFF}/C_{OFF} - T_a

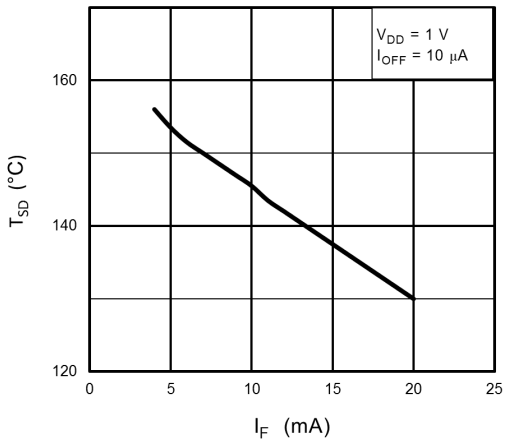


Fig. 14.14 T_{SD} - I_F

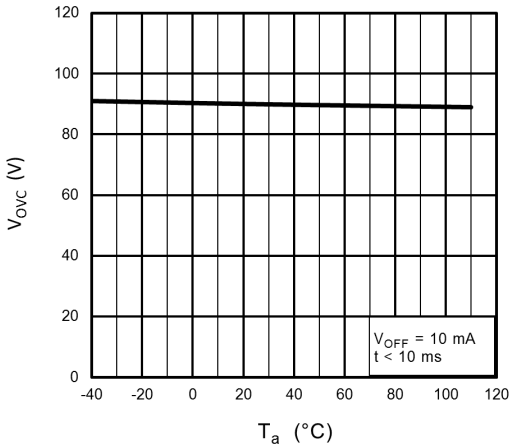


Fig. 14.15 V_{OVC} - T_a

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

15. Protection Operation

15.1. Over temperature protection

To prevent damage due to temperature rise, the outputs are turned off when the sensing chip in control circuit exceeds the over Thermal shutdown temperature (T_{SD}). Once this protection activate, the output turn to latch off statement and turn off regardless sensing chip temperature. To reset this statement, you should set LED input forward current zero once.

15.2. Over voltage protection

Over voltage protection is a function that when over voltage surge applied, output part clamps and keeps voltage defference between itself. This protection is only for short time surge. So if it is long time applied and exceeds V_{OVC}, it might break.

15.3. Timing Diagrams

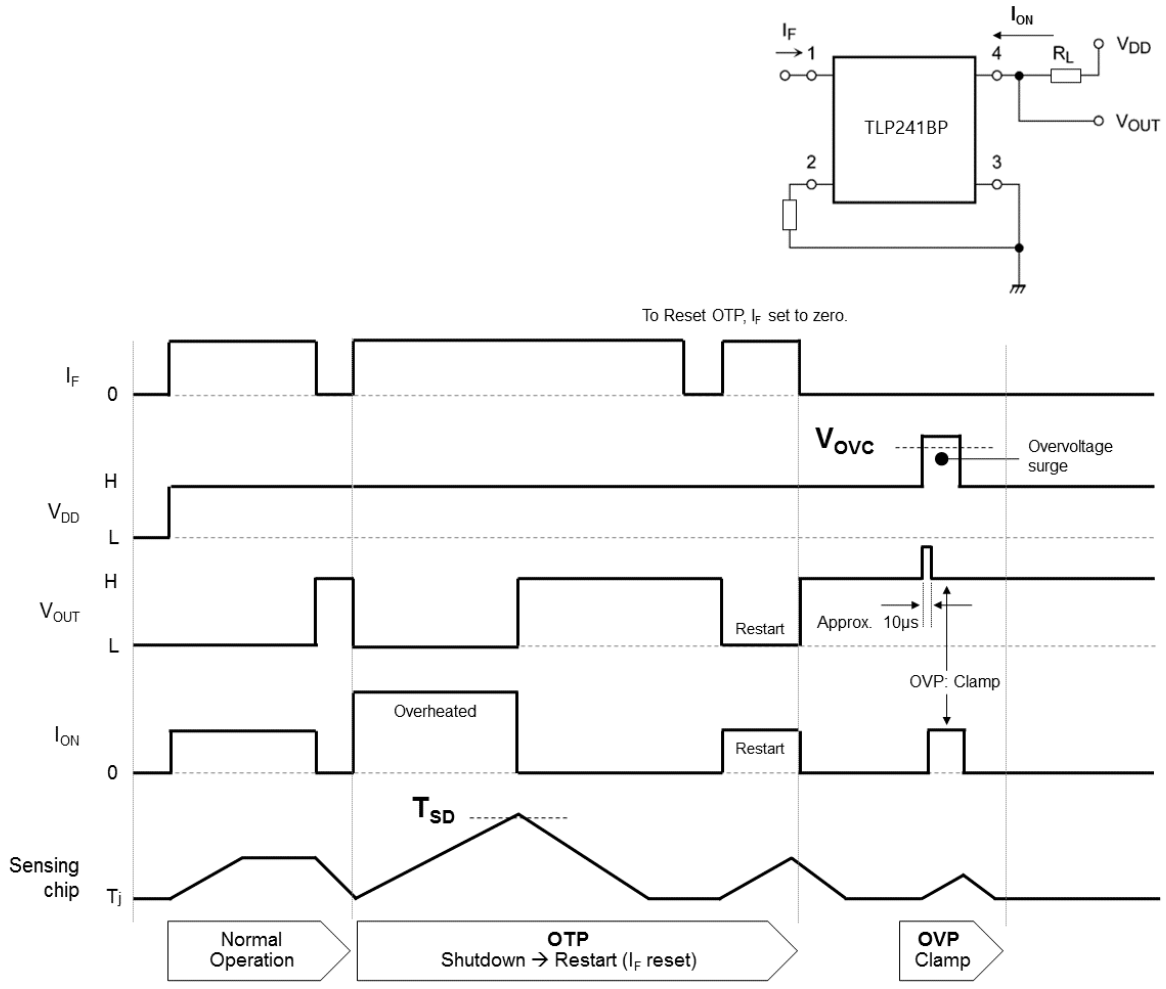
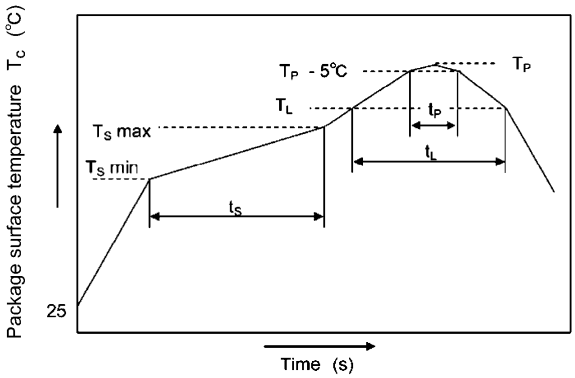


Fig. 15.3.1 Timing diagram

Note: 10μs in this figure is reference value

16. Case with reflow

- When using soldering reflow.
  The soldering temperature profile is based on the package surface temperature.
  (See the figure shown below, which is based on the package surface temperature.)
  Reflow soldering must be performed once or twice.
  The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



	Symbol	Min	Max	Unit
Preheat temperature	T_S	150	200	°C
Preheat time	t_S	60	120	s
Ramp-up rate (T_L to T_P)			3	°C/s
Liquidus temperature	T_L	217		°C
Time above T_L	t_L	60	150	s
Peak temperature	T_P		260	°C
Time during which T_c is between (T_P – 5) and T_P	t_P		30	s
Ramp-down rate (T_P to T_L)			6	°C/s

An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
  Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
  Mounting condition of 260 °C within 10 seconds is recommended.
  Flow soldering must be performed once.
- When using soldering Iron
  Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
  Heating by soldering iron must be done only once per lead.

16.1. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

17. Ordering Information (Example of Item Name)

Item Name	Packaging (Note 1)	VDE Option	Packing (MOQ)
TLP241BP(E	TH		Magazine (100 pcs)
TLP241BP(LF1,E	LF1		Magazine (100 pcs)
TLP241BP(LF5,E	LF5		Magazine (100 pcs)
TLP241BP(TP1,E	LF1		Tape and reel (1500 pcs)
TLP241BP(TP5,E	LF5		Tape and reel (1500 pcs)
TLP241BP(D4,E	TH	EN 60747-5-5	Magazine (100 pcs)
TLP241BP(D4LF1,E	LF1	EN 60747-5-5	Magazine (100 pcs)
TLP241BP(D4LF5,E	LF5	EN 60747-5-5	Magazine (100 pcs)
TLP241BP(D4TP1,E	LF1	EN 60747-5-5	Tape and reel (1500 pcs)
TLP241BP(D4TP5,E	LF5	EN 60747-5-5	Tape and reel (1500 pcs)
TLP241BPF(E	TH, Wide forming		Magazine (100 pcs)
TLP241BPF(LF4,E	LF4, Wide forming		Magazine (100 pcs)
TLP241BPF(TP4,E	LF4, Wide forming		Tape and reel (1000 pcs)
TLP241BPF(D4,E	TH, Wide forming	EN 60747-5-5	Magazine (100 pcs)
TLP241BPF(D4LF4,E	LF4, Wide forming	EN 60747-5-5	Magazine (100 pcs)
TLP241BPF(D4TP4,E	LF4, Wide forming	EN 60747-5-5	Tape and reel (1000 pcs)

Note 1: TH: Through-hole, LF: Lead forming for surface mount

18. Devices in Halogen-Free Resin Packages

・This product is Halogen-Free

Toshiba Electronic Devices & Storage Corporation ("Toshiba") defines a "Halogen-Free resin semiconductor product" as a semiconductor product in which:

(1) the encapsulating resins do not contain any of the following elements: bromine (Br), chlorine (Cl) and antimony (Sb), respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the encapsulating resins, and/or

(2) the resin portion(s) in printed circuit boards do not contain any of the following elements: bromine, chlorine and antimony, respectively, in an amount exceeding 0.09 weight percent, and do not contain chlorine and bromine in an aggregate amount exceeding 0.15 weight percent of the each resin portion(s) in printed circuit boards.

For avoidance of doubt, "Halogen-Free resin semiconductor product" does not mean, and Toshiba does not make any warranty of any kind, that said semiconductor product is entirely free of antimony or of any of the following elements of the halogen family: bromine, chlorine, iodine (I), fluorine (F) and astatine (At).

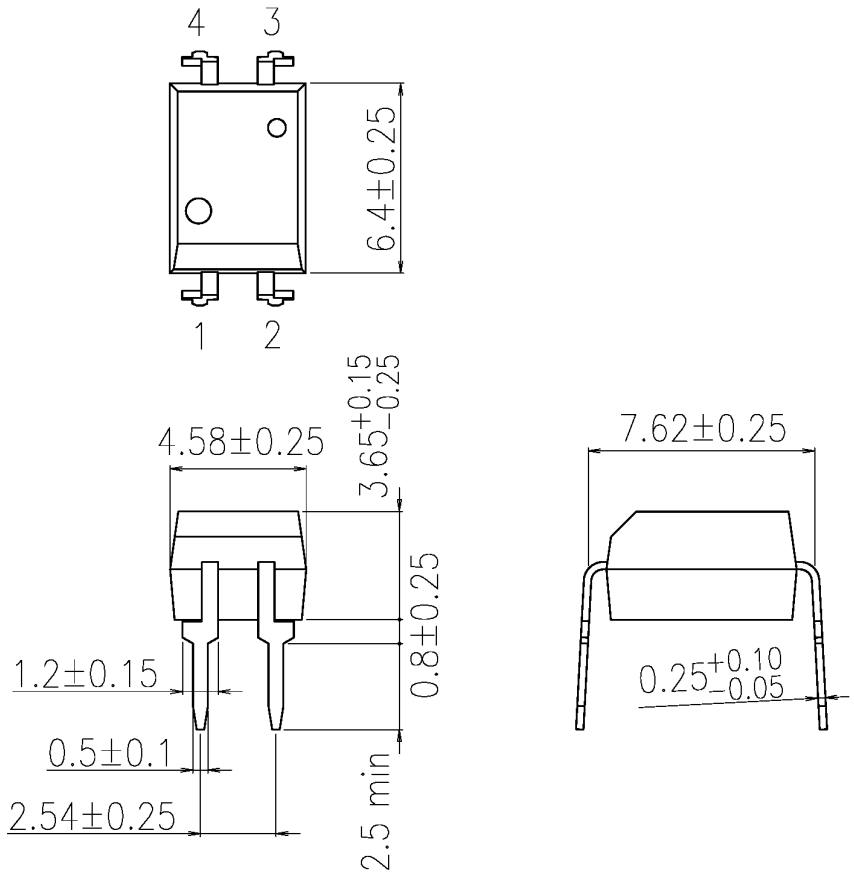
In addition, a Halogen-Free resin semiconductor product may contain antimony and/or any of the elements of the halogen family as mentioned in the above paragraph in one or more portion(s) of the semiconductor product other than the encapsulating resins and the resin portion(s) in printed circuit boards.

The information provided herein is accurate as of the date that it was provided, to the best of the knowledge and belief of the Toshiba Electronic Devices & Storage Corporation ("Toshiba"), Toshiba bases such knowledge and belief on information provided by third parties, and Toshiba makes no representation or warranty as to the accuracy of such third party information. Toshiba has taken and will continue to take, reasonable steps to provide accurate information to its customers, but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.

Package Dimensions

Unit: mm

TLP241BP



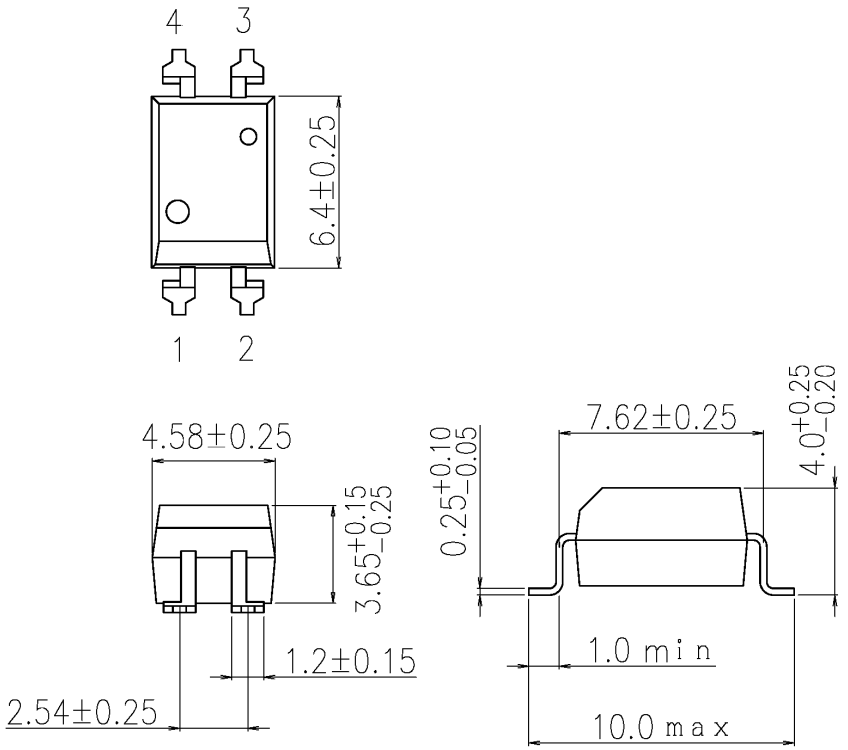
Weight: 0.26 g (typ.)

Package Name(s)
TOSHIBA: 11-5B2S

Package Dimensions

Unit: mm

TLP241BP(LF1,TP1)



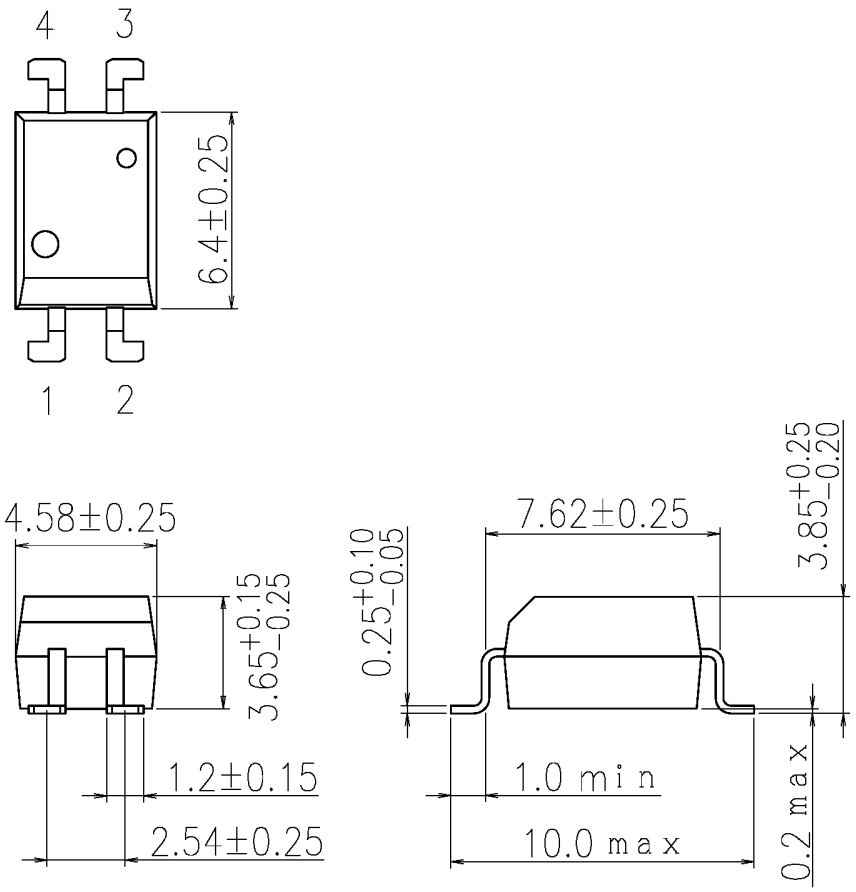
Weight: 0.25 g (typ.)

Package Name(s)
TOSHIBA: 11-5B201S

Package Dimensions

Unit: mm

TLP241BP(LF5,TP5)



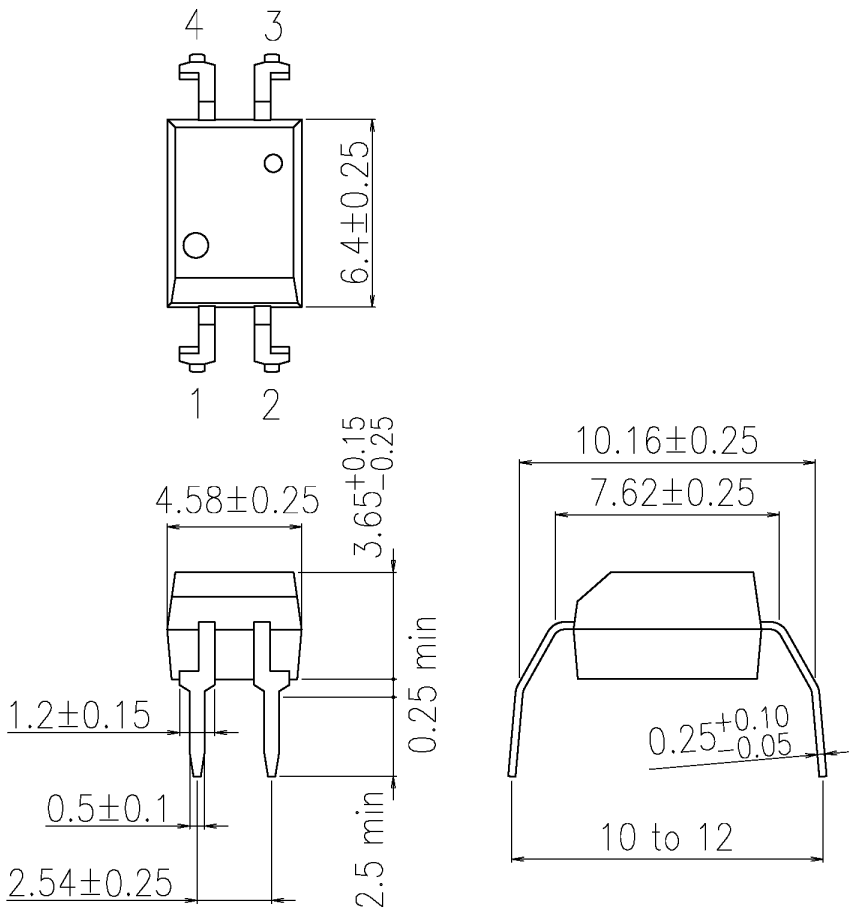
Weight: 0.25 g (typ.)

Package Name(s)
TOSHIBA: 11-5B205S

Package Dimensions

Unit: mm

TLP241BPF



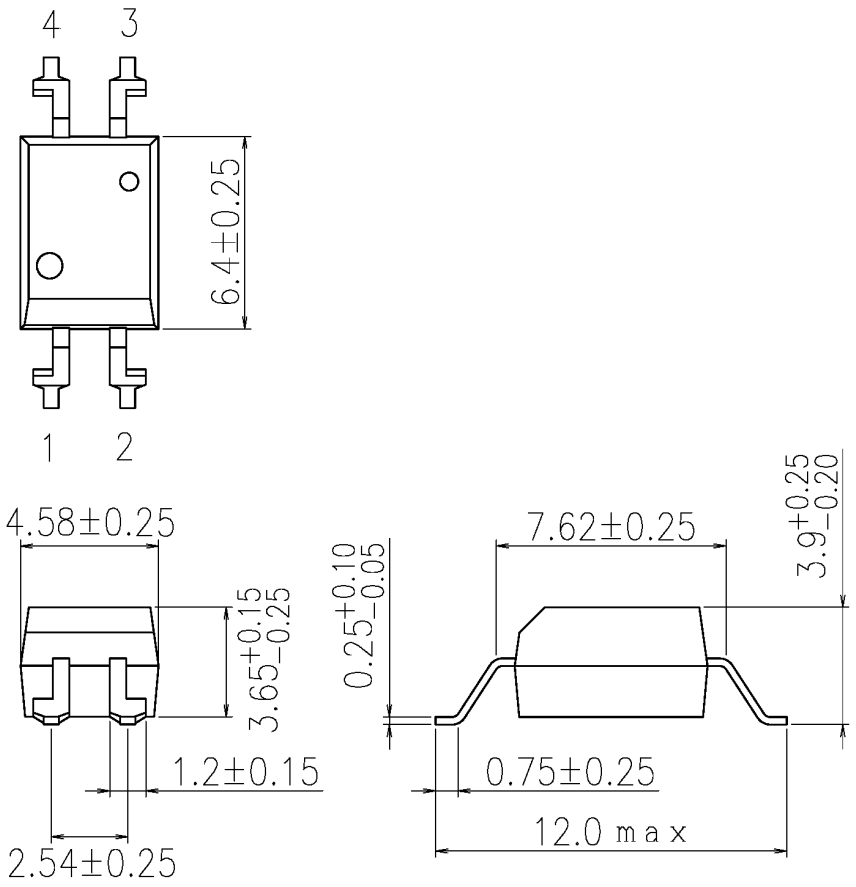
Weight: 0.26 g (typ.)

Package Name(s)
TOSHIBA: 11-5B202S

Package Dimensions

Unit: mm

TLP241BPF(LF4,TP4)



Weight: 0.25 g (typ.)

Package Name(s)
TOSHIBA: 11-5B204S

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